



Material Content Data Sheet



Sales Product Name		BSC500N20NS3 G		Issued		29. August 2013		
MA#		MA001000238						
Package		PG-TDSON-8-1		Weight*		120.30 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.061	2.54	2.54	25447	25447
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		314	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		94	
	non noble metal	copper	7440-50-8	37.762	31.38	31.42	313884	314292
wire	non noble metal	copper	7440-50-8	0.059	0.05	0.05	488	488
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		688	
	plastics	epoxy resin	-	5.878	4.89		48856	
	inorganic material	silicondioxide	60676-86-0	35.431	29.45	34.41	294513	344057
leadfinish	non noble metal	tin	7440-31-5	1.452	1.21	1.21	12067	12067
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1376	1376
solder	non noble metal	tin	7440-31-5	0.054	0.04		450	
	noble metal	silver	7440-22-4	0.068	0.06		563	
	non noble metal	lead	7439-92-1	2.587	2.15	2.25	21507	22520
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		94	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	copper	7440-50-8	11.320	9.41	9.42	94095	94217
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		186	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	copper	7440-50-8	22.292	18.53	18.56	185294	185536
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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